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L Number	Hits	Search Text	DB	Time stamp
-	31751	power and ground\$ and signal and @ad<19990719 and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/04/19 20:52
-	684	(power and ground\$ and signal and @ad<19990719 and substrate) and (conductive adj adhesive)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT;	2003/04/19 20:54
-	92	((power and ground\$ and signal and @ad<19990719 and substrate) and (conductive adj adhesive)) and (ground\$ adj potential)	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/21 13:10
-	31751	power and ground\$ and signal and @ad<19990719 and substrate	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/04/21 12:46
-	92	((power and ground\$ and signal and @ad<19990719 and substrate) and (conductive adj adhesive)) and (ground\$ adj potential)	IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 13:12